

Magnetic Head Chip Bonding Device

ABSTRACT

A magnetic head chip bonding device for bonding plural magnetic head chip to a base member to produce a composite type magnetic head is disclosed. The device includes a magnetic head chip retention unit for applying the pressure to the magnetic head chip for applying the magnetic head chip against the base member, and a magnetic head chip holding unit for holding the magnetic head chip. The device also includes a magnetic head chip detection unit for detecting the position of the magnetic head chip and a magnetic head chip shifting unit for shifting the magnetic head chip and the magnetic head chip holding unit responsive to an output of the magnetic head chip position detection unit. The pressure exerted by the magnetic head chip retention unit on the magnetic head chip is preferably variable, and the magnetic head chip holding unit preferably is made up of a pair of supporting members clamping the magnetic head chip in-between. The device renders it possible to bond the magnetic head chips to the base member in position without requiring operation skill.

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